

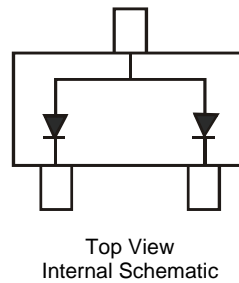
## DUAL SURFACE MOUNT LOW LEAKAGE DIODE

### Features

- Surface Mount Package Ideally Suited for Automated Insertion
- Very Low Leakage Current
- **Lead, Halogen, and Antimony Free, RoHS Compliant (Note 1)**
- **"Green" Device (Notes 2 & 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

### Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Matte Tin Finish annealed over Alloy 42 leadframe (Lead Free Plating). Solderable per MIL-STD-202, Method 208
- Polarity: See Diagram
- Weight: 0.008 grams (approximate)

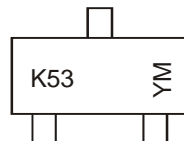


### Ordering Information (Note 4)

Part Number	Qualification	Case	Packaging
BAW156-7-F	Commercial	SOT23	3,000/Tape & Reel
BAW156-13-F	Commercial	SOT23	10,000/Tape & Reel
BAW156Q-7-F	Automotive	SOT23	3,000/Tape & Reel
BAW156Q-13-F	Automotive	SOT23	10,000/Tape & Reel

- Notes:
1. No purposefully added lead.
  2. Product manufactured with Date Code V9 (week 33, 2008) and newer are built with Green Molding Compound. Product manufactured prior to Date Code V9 are built with Non-Green Molding Compound and may contain Halogens or Sb<sub>2</sub>O<sub>3</sub> Fire Retardants.
  3. Diodes Inc.'s "Green" Policy can be found on our website at <http://www.diodes.com>
  4. For packaging details, go to our website at <http://www.diodes.com>.

### Marking Information



K53 = Product Type Marking Code  
 YM = Date Code Marking  
 Y = Year (ex: Y = 2011)  
 M = Month (ex: 9 = September)

#### Date Code Key

Year	1998	1999	.....	2006	2007	2008	2009	2010	2011	2012	2013	2014	2015	2016	2017
Code	J	K	.....	T	U	V	W	X	Y	Z	A	B	C	D	E

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

**Maximum Ratings** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage	V <sub>RRM</sub>	85	V
Working Peak Reverse Voltage	V <sub>RWM</sub>		
DC Blocking Voltage	V <sub>R</sub>		
RMS Reverse Voltage	V <sub>R(RMS)</sub>	60	V
Forward Continuous Current	I <sub>FM</sub>	160	mA
(Note 5)		140	
Repetitive Peak Forward Current (Note 5)	I <sub>FRM</sub>	500	mA
Non-Repetitive Peak Forward Surge Current	I <sub>FSM</sub>	@ t = 1.0μs	4.0
		@ t = 1.0ms	1.0
		@ t = 1.0s	0.5

**Thermal Characteristics**

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	250	mW
Thermal Resistance Junction to Ambient Air (Note 5)	R <sub>θJA</sub>	500	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-65 to +150	°C

**Electrical Characteristics** @T<sub>A</sub> = 25°C unless otherwise specified

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 6)	V <sub>(BR)R</sub>	85	—	—	V	I <sub>R</sub> = 100μA
Forward Voltage	V <sub>F</sub>	—	—	0.90 1.0 1.1 1.25	V	I <sub>F</sub> = 1.0mA I <sub>F</sub> = 10mA I <sub>F</sub> = 50mA I <sub>F</sub> = 150mA
Leakage Current (Note 6)	I <sub>R</sub>	—	—	5.0 80	nA nA	V <sub>R</sub> = 75V V <sub>R</sub> = 75V, T <sub>J</sub> = 150°C
Total Capacitance	C <sub>T</sub>	—	3	—	pF	V <sub>R</sub> = 0, f = 1.0MHz
Reverse Recovery Time	t <sub>rr</sub>	—	—	3.0	μs	I <sub>F</sub> = I <sub>R</sub> = 10mA, I <sub>rr</sub> = 0.1 x I <sub>R</sub> , R <sub>L</sub> = 100Ω

Notes: 5. Part mounted on FR-4 board with recommended pad layout, which can be found on our website at <http://www.diodes.com>.  
6. Short duration pulse test used to minimize self-heating effect.

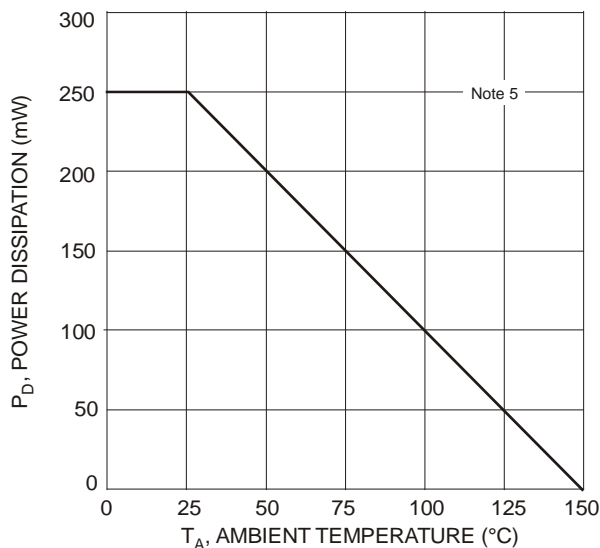


Fig. 1 Power Derating Curve, Total Package

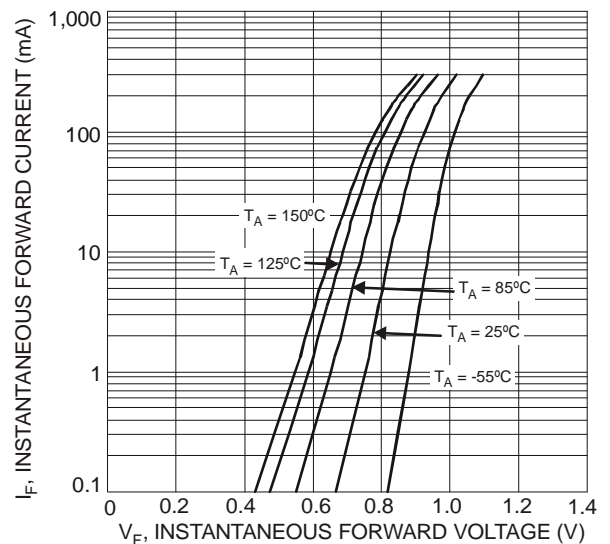


Fig. 2 Typical Forward Characteristics, Per Element

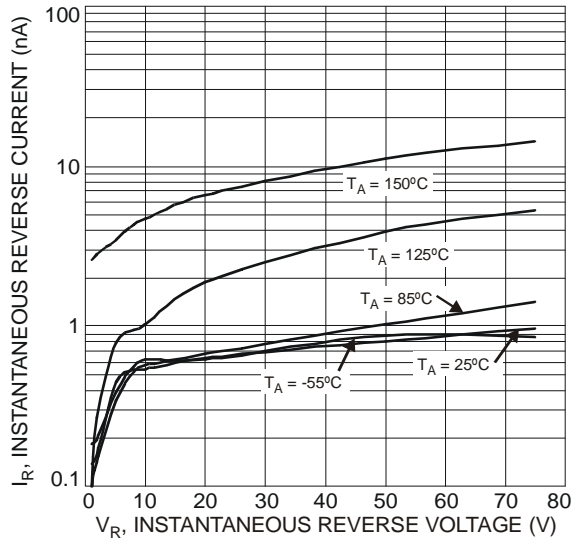


Fig. 3 Typical Reverse Characteristics, Per Element

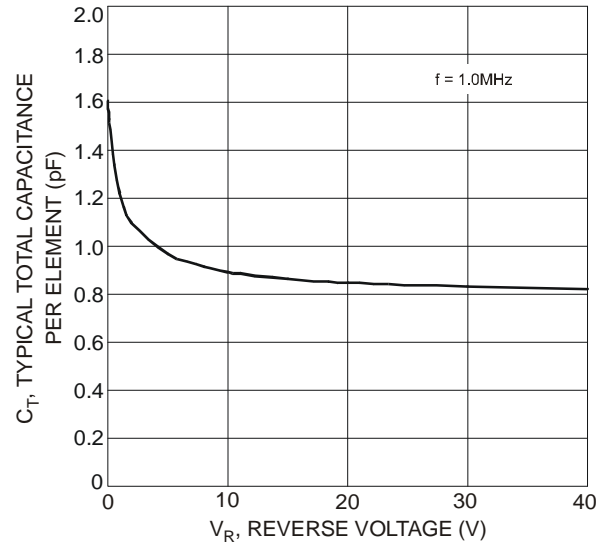
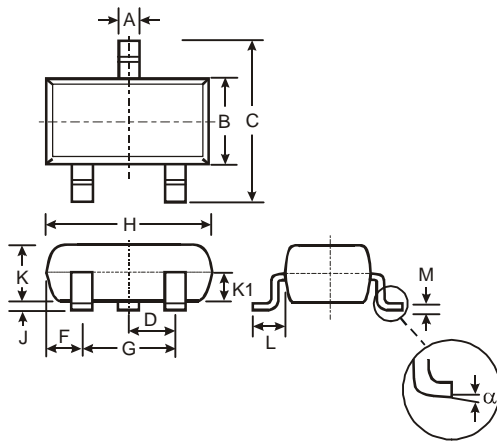


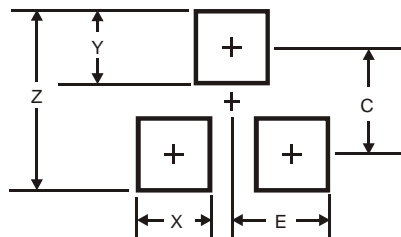
Fig. 4 Typical Capacitance vs. Reverse Voltage

**Package Outline Dimensions**



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
$\alpha$	0°	8°	-
All Dimensions in mm			

**Suggested Pad Layout**



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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